In the Claims:

Please amend the claims as follows:

1. (Currently Amended) A [[C]]configuration [[(100)]] comprising: an active optical component [[20)]] that is electrically connected to a flexible electronic board [[(10)]], the active optical component being designed to be aligned with an optical system, [[characterized in that]] characterized in that the electronic board is a flexible circuit with a high density of interconnections, called a HDI flexible circuit, with an upper longitudinal surface [[(10a)]] that comprises a metallic brazing sector [[(6)]] in contact with a microwave transmission path [[(3)]] of the HDI flexible circuit, [[and [also characterized] in that]] and also characterized in that the active optical component on one of its surfaces [[(20a)]], i.e. the contact surface, comprises a metallic contact sector [[(21)]] that coincides directly with the metallic brazing sector by turning said active optical component over onto the HDI flexible circuit.

2. (Currently Amended) The [[C]]configuration [[(100)]] ~~as claimed in~~ of claim 1, [[characterized in that]] characterized in that the metallic brazing sector [[(6)]] comprises a network of metallic brazing contact studs [[(61, 62)]] with a diameter of roughly 30 μm.

3. (Currently Amended) The [[C]]configuration [[(100)]] ~~as claimed in~~ of claim 2, [[characterized in that]] characterized in that the upper longitudinal surface [[(10a)]] of the HDI flexible circuit [[(10)]] comprises a zone of electrical insulation [[(51)]] in an essentially annular configuration around one of the ends of the microwave transmission path [[(3)]] and extending through a flared electrical insulation zone [[(52)]], [[**and [also characterized] in that**]] and also characterized in that one of said metallic brazing contact studs, i.e. the central contact [[(61)]], is located on said end and the other metallic brazing contact studs [[(62)]] are distributed essentially in a semi-circle or circles on a ground conductive zone [[(4)]] in the vicinity of the side of said annular electrical insulation zone.

4. (Currently Amended) The [[C]]configuration [[(100)]] ~~as claimed in~~ of claim 3,

[[characterized in that]] characterized in that the flared electrical insulation zone [[(52)]] ends in a narrowed electrical insulation zone [[(53)]].

5. (Currently Amended) The [[C]]configuration [[(100)]] ~~as claimed in one of claims~~ of claim 1 [[to 4]], [[characterized in that]] characterized in that the active optical component can be chosen from among a photodiode [[(20)]] that is able to receive modulated optical signal by the longitudinal surface [[(20b)]], i.e. the receiving surface, parallel to the contact surface [[(20a)]], and a laser that is able to supply modulated optical signals by the longitudinal surface, i.e. the transmission surface, parallel to the contact surface.

6. (Currently Amended) The [[C]]configuration [[(100)]] ~~as claimed in one~~ of [[claims]] claim 1 [[to 5]], [[characterized in that]] characterized in that the upper longitudinal surface [[(10a)]] of the HDI flexible circuit [[(10)]] comprises another metallic brazing sector [[(7)]], said other sector being in contact with one end of the microwave transmission path [[(3)]] and with another microwave transmission path [[(3')]] of the HDI flexible circuit [[(10)]], [[and [also characterized] in that]] and also characterized in that it comprises an active electronic component [[(50)]] that has, on one of its surfaces, i.e. the contact surface [[(50a)]], a metallic contact sector that coincides directly with said other metallic brazing sector by turning the active electronic component over onto the HDI flexible circuit.

7. (Currently Amended) An [[O]]optoelectronic device [[(300)]] that is equipped with a box [[(60)]] [[characterized in that]] characterized in that it comprises the configuration [[(100)]] as claimed in ~~one of claims~~ claim 1 [[to 6]] and an optical system [[(30)]] aligned with the active optical component [[(20)]], the configuration and the optical system being kept in the box.

8. (Currently Amended) The [[O]]optoelectronic device [[(300)]] ~~as claimed in~~ of claim 7, [[characterized in that]] characterized in that when the active optical component [[(20)]] is chosen from among said photodiode and said laser, the HDI flexible circuit [[(10)]] is bent and the upper longitudinal surface [[(10a)]] comprises a first part, with respect to the bottom of the box [[(61)]] extended by a second part containing said brazing sector [[(6)]] with respect to one

of the lateral transverse surfaces [[(62)]] of the box.

9. (Currently Amended) The [[O]]optoelectronic device [[(300)]] ~~as claimed in~~ of claim 8, [[characterized in that]] characterized in that the receiving surface [[(20b)]] of the active optical component [[(20)]] is attached by an optically transparent adhesive [[(40)]] to one end of an optical fiber [[(30)]] integral with said lateral transverse surface [[(62)]] of the box.

10. (Currently Amended) A [[P]]process of manufacture of a configuration [[(100)]] as claimed in ~~one of claims~~ claim1 [[to 6]], [[characterized in that]] characterized in that it comprises the following stages:

- the stage of formation of the metallic brazing sector [[(6)]] of the HDI flexible circuit [[(10)]] by physical vapor phase deposition,
- the stage of formation of the metallic contact sector [[(21)]] of the active optical component [[(20)]],
- the stage of installation of the active optical component [[(20)]] on the HDI flexible circuit by turning it over and brazing.

11. (Currently Amended) The [[P]]process of manufacture of a configuration [[(100)]] ~~as claimed in~~ of claim 10, [[characterized in that]] characterized in that it comprises the following stages

- the stage of formation of another metallic brazing sector (7) of the HDI flexible circuit [[(10)]] by physical vapor phase deposition,

the stage of formation of the metallic contact sector of the active electronic component [[(50)]],

the stage of installation of the active electronic component on the HDI flexible circuit by turning it over and brazing.

12. (Currently Amended) A [[P]]process of manufacture of an optoelectronic device [[(300)]] ~~as claimed in one~~ of [[claims]] claim 8 [[or 9]], [[characterized in that]] characterized in that it comprises the stages of manufacture of a configuration [[(100)]] ~~as claimed in one~~ of

[[claims]] claim 10 ~~or 11~~ [[and [also characterized] in that]] and also characterized in that it comprises a stage of supporting the configuration and the optical system in said box including the bending of the HDI flexible circuit [[(10)]].

13. (Currently Amended) The [[P]]process of manufacture of an optoelectronic device [[(300)]] ~~as claimed in~~ of claim 12, [[characterized in that]] characterized in that the optical system comprises an optical fiber [[(30)]], wherein the stage of supporting the configuration and the optical fiber in the box includes the following:

- bonding the optical fiber in one of the lateral transverse surfaces [[(62)]] and bonding the active electronic component [[(50)]] in the bottom of the box [[(61)]],
- soldering the end of the HDI flexible circuit [[(10)]] to one interconnection located at the level of the other of the lateral transverse surfaces of the box [[(63)]].